



## Time-Series Measurements of 3D Shape and Deformation Using Image Analysis

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Deadline for manuscript submissions:

**closed (30 April 2022)**

### Message from the Guest Editors

This special issue focuses on time-series measurements of 3D shape and deformation using image analysis. Time-series measurements of stress and strain are also included. Time-series measurements are required to investigate dynamic behavior of materials and structures.

The research topics will (non-exclusively) include:

- 3D shape and deformation measurement
- Stress and strain measurement
- Time-series measurement
- Image analysis
- Optical method
- Digital image correlation (DIC)
- Sampling moiré method
- Robot vision
- Experimental mechanics
- Nondestructive inspection
- Civil engineering
- Vibration measurement





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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